

DATA SHEET

74LVC11 Triple 3-input AND gate

Product specification
Supersedes data of 1998 Apr 28

2004 Jan 13

Triple 3-input AND gate

74LVC11

FEATURES

- Wide supply voltage range from 1.2 to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output capability: standard
- I_{CC} category: SSI
- In accordance with JEDEC standard no. 8-1A
- ESD protection:
HBM EIA/JESD22-A114-A exceeds 2000 V
MM EIA/JESD22-A115-A exceeds 200 V.

DESCRIPTION

The 74LVC11 is a high-performance, low power, low-voltage, Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

The 74LVC11 provides the 3-input AND function.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; t_r = t_f ≤ 2.5 ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	propagation delay nA, nB, nC to nY	C _L = 50 pF; V _{CC} = 3.3 V	3.7	ns
C _I	input capacitance		5.0	pF
C _{PD}	power dissipation capacitance per gate	notes 1 and 2	26	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

N = total switching outputs;

Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

2. The condition is V_I = GND to V_{CC}.

ORDERING INFORMATION

TYPE NUMBER	TEMPERATURE RANGE	PACKAGE			
		PINS	PACKAGE	MATERIAL	CODE
74LVC11D	-40 to +85 °C	14	SO14	plastic	SOT108-1
74LVC11DB	-40 to +85 °C	14	SSOP14	plastic	SOT337-1
74LVC11PW	-40 to +85 °C	14	TSSOP14	plastic	SOT402-1
74LVC11BQ	-40 to +85 °C	14	DHVQFN14	plastic	SOT762-1

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FUNCTION TABLE

See note 1.

INPUT			OUTPUT
nA	nB	nC	nY
L	L	L	L
L	L	H	L
L	H	L	L
L	H	H	L
H	L	L	L
H	L	H	L
H	H	L	L
H	H	H	H

Note

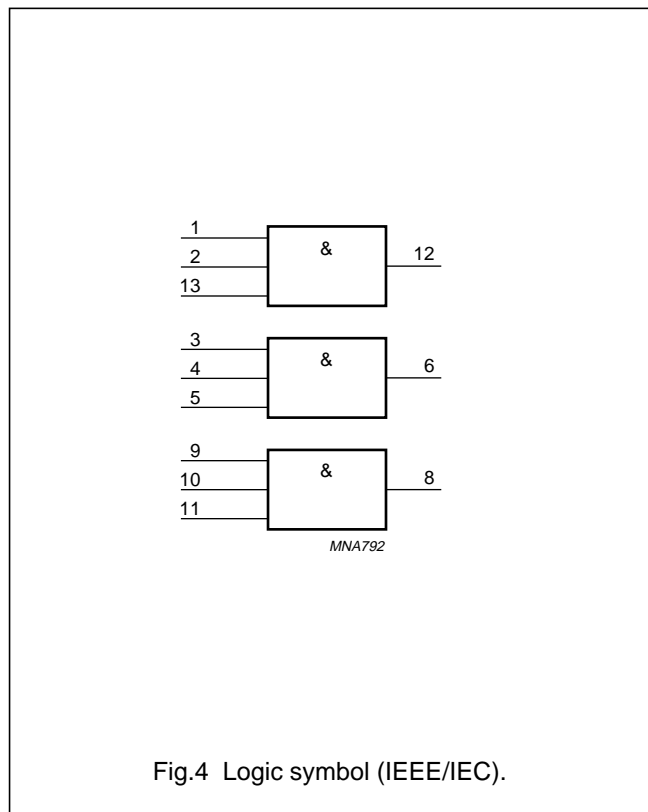
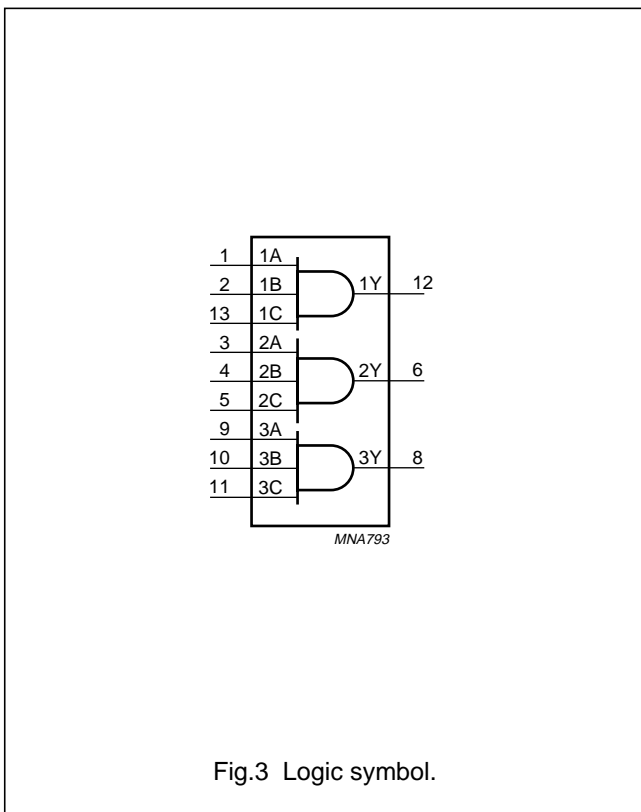
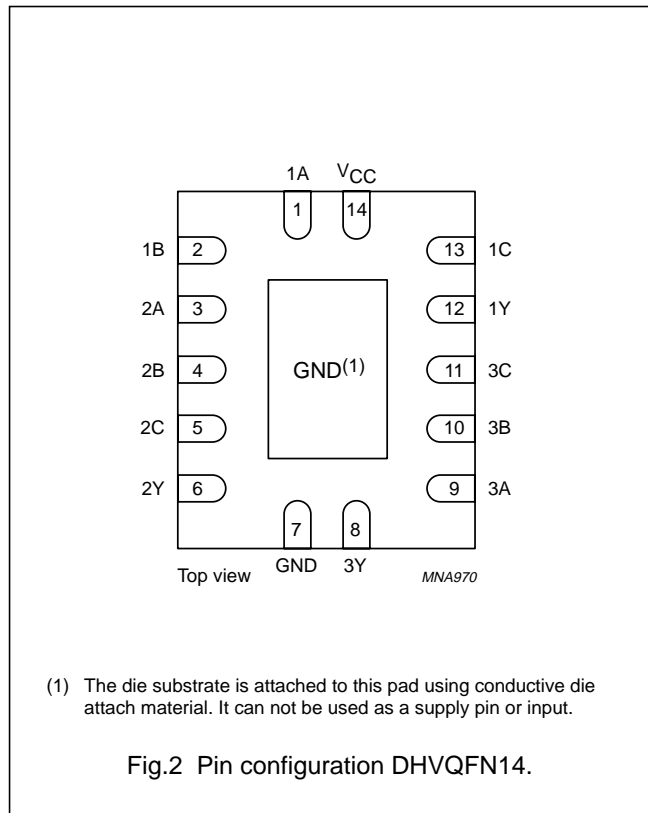
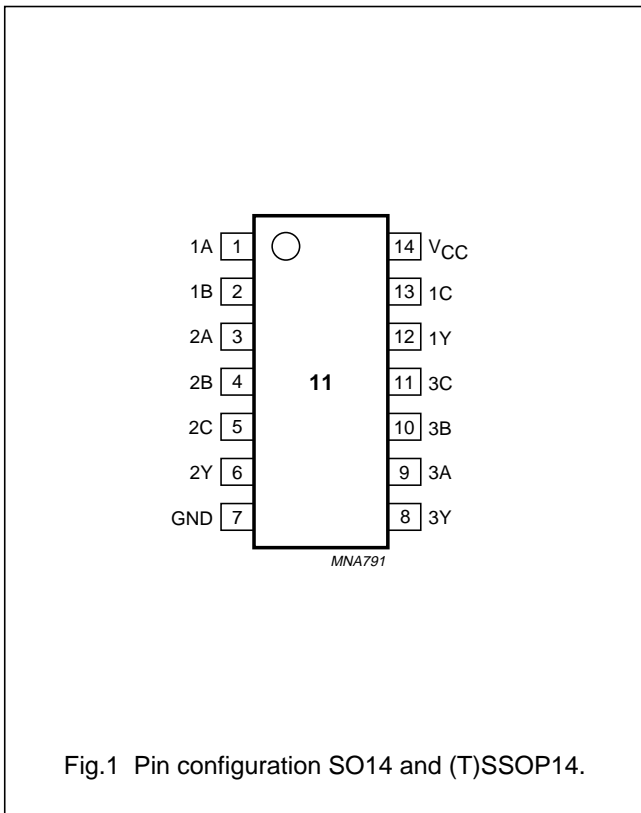
1. H = HIGH voltage level.
L = LOW voltage level.

PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1B	data input
3	2A	data input
4	2B	data input
5	2C	data input
6	2Y	data output
7	GND	ground (0 V)
8	3Y	data output
9	3A	data input
10	3B	data input
11	3C	data input
12	1Y	data output
13	1C	data input
14	V _{CC}	positive supply voltage

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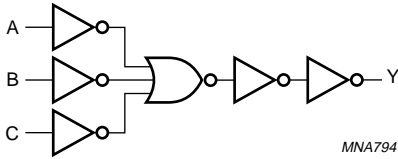


Fig.5 Logic diagram (one gate).

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage	for maximum speed performance	2.7	3.6	V
		for low-voltage applications	1.2	3.6	V
V _I	input voltage		0	5.5	V
V _O	output voltage		0	V _{CC}	V
T _{amb}	operating ambient temperature		-40	+85	°C
t _r , t _f	input rise and fall times	V _{CC} = 1.2 to 2.7 V	0	20	ns/V
		V _{CC} = 2.7 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input diode current	V _I < 0	-	-50	mA
V _I	input voltage	note 1	-0.5	+6.5	V
I _{OK}	output diode current	V _O > V _{CC} or V _O < 0	-	±50	mA
V _O	output voltage	note 1	-0.5	V _{CC} + 0.5	V
I _O	output source or sink current	V _O = 0 to V _{CC}	-	±50	mA
I _{GND} , I _{CC}	V _{CC} or GND current		-	±100	mA
T _{stg}	storage temperature range		-65	+150	°C
P _{tot}	power dissipation	T _{amb} = -40 to +125 °C; note 2	-	500	mW

Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- For SO14 packages: above 70 °C the value of P_D derates linearly with 8 mW/K.
For (T)SSOP14 packages: above 60 °C the value of P_D derates linearly with 5.5 mW/K.
For DHVQFN14 packages: above 60 °C the value of P_D derates linearly with 4.5 mW/K.

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DC CHARACTERISTICS

At recommended operating conditions voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		OTHER	V _{CC} (V)				
T_{amb} = -40 °C to +85 °C							
V _{IH}	HIGH level input voltage		1.2	V _{CC}	-	-	V
			2.7 to 3.6	2.0	-	-	V
V _{IL}	LOW-level input voltage		1.2	-	-	GND	V
			2.7 to 3.6	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} I _O = -12 mA	2.7	V _{CC} - 0.5	-	-	V
		I _O = -100 µA	3.0	V _{CC} - 0.2	V _{CC}	-	V
		I _O = -12 mA	3.0	V _{CC} - 0.6	-	-	V
		I _O = -24 mA	3.0	V _{CC} - 1.0	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} I _O = 12 mA	2.7	-	-	0.40	V
		I _O = 100 µA	3.0	-	GND	0.20	V
		I _O = 24 mA	3.0	-	-	0.55	V
I _{LI}	input leakage current	V _I = 5.5 V or GND	3.6	-	±0.1	±5	µA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	3.6	-	0.1	10	µA
ΔI _{CC}	additional quiescent supply current per input pin	V _I = V _{CC} - 0.6 V; I _O = 0	2.7 to 3.6	-	5	500	µA

Note

- All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

AC CHARACTERISTICSGND = 0 V; t_r = t_f ≤ 2.5 ns; C_L = 50 pF; R_L = 500 Ω.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		WAVEFORMS	V _{CC} (V)				
T_{amb} = -40 to +85 °C							
t _{PHL} /t _{PLH}	propagation delay	see Figs 6 and 7	2.7	-	-	7.0	ns
			3.0 to 3.6	-	3.7	6.2	ns

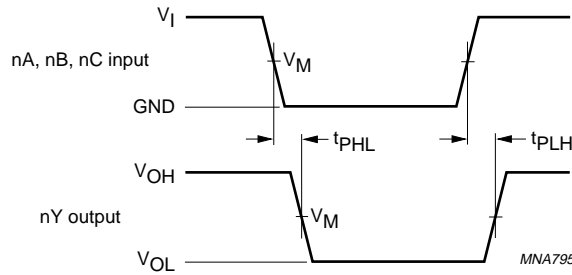
Note

- Typical value is measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

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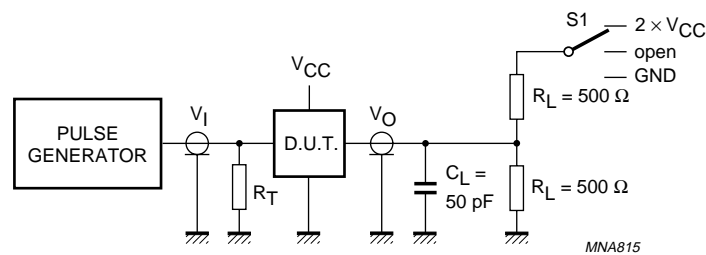
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AC WAVEFORMS



$V_M = 1.5\text{ V}$ at $V_{CC} \geq 2.7\text{ V}$.
 $V_M = 0.5V_{CC}$ at $V_{CC} < 2.7\text{ V}$.
 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

Fig.6 Input (nA, nB and nC) to output (nY) propagation delays.



SWITCH POSITION	
TEST	S1
t_{PLH}/t_{PHL}	open

V_{CC}	V_I
$< 2.7\text{ V}$	V_{CC}
$2.7\text{ to }3.6\text{ V}$	2.7 V

Definitions for test circuit:
 R_L = load resistor.
 C_L = load capacitance including jig and probe capacitance.
 R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig.7 Load circuitry for switching times.

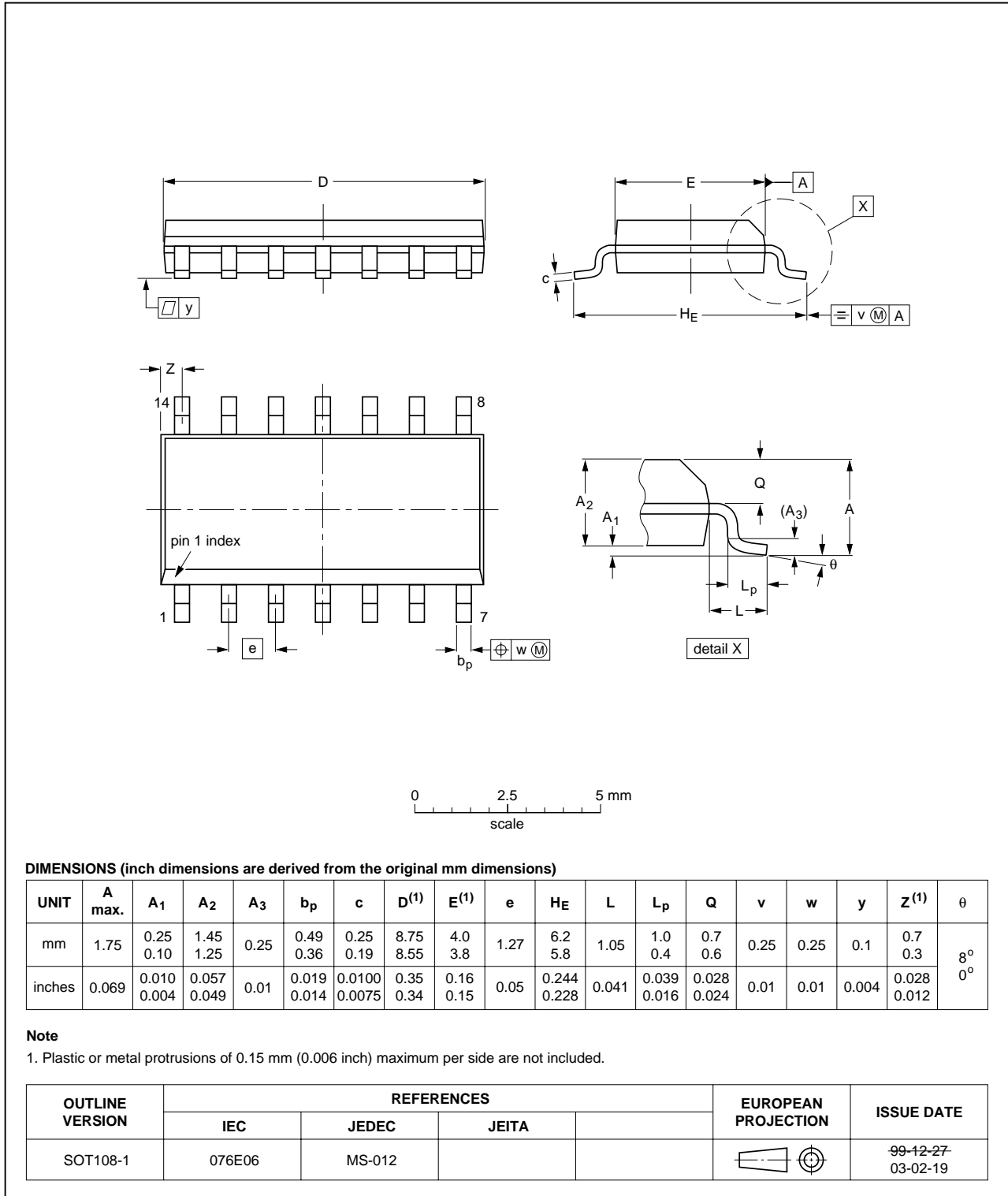
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PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

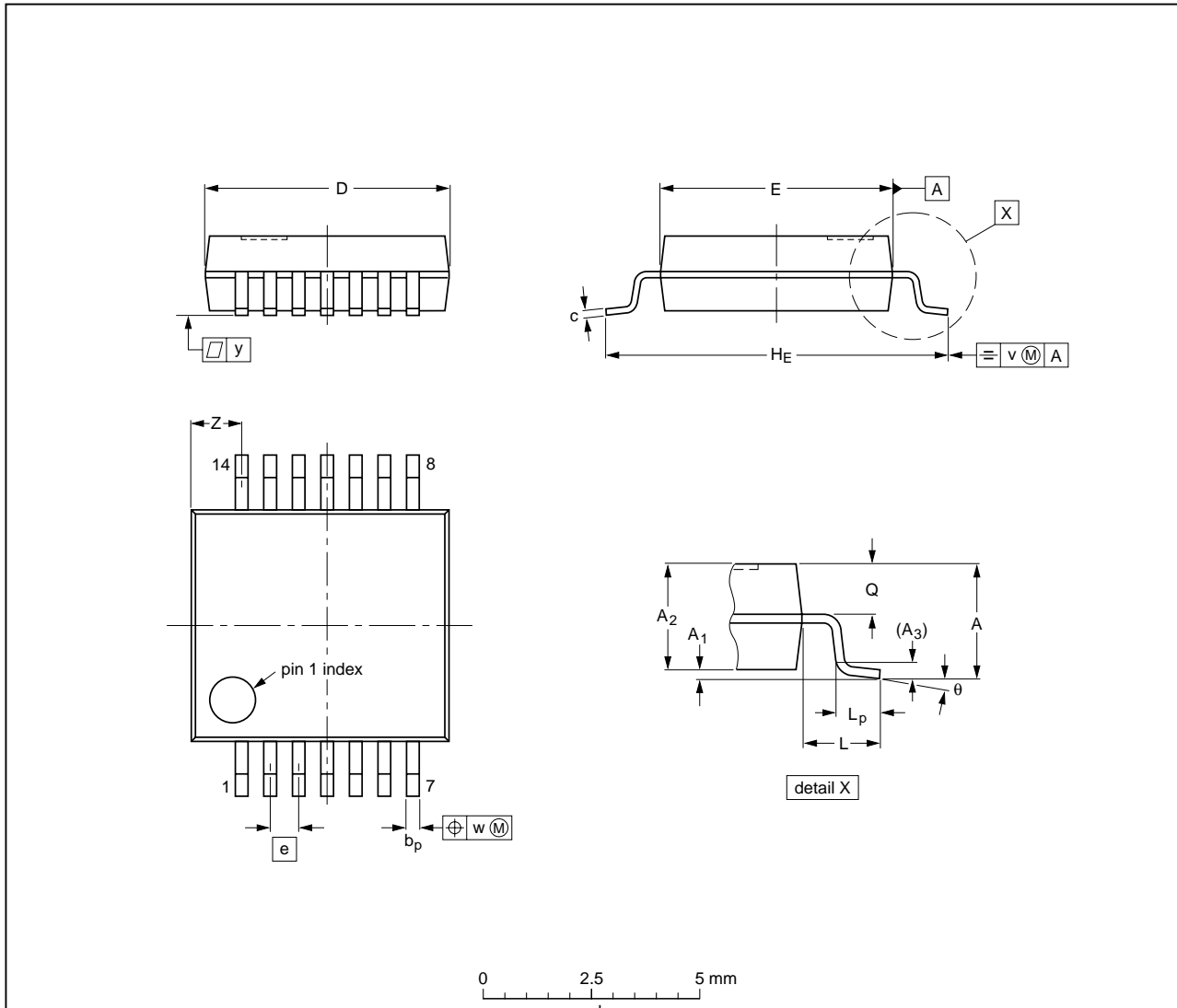


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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

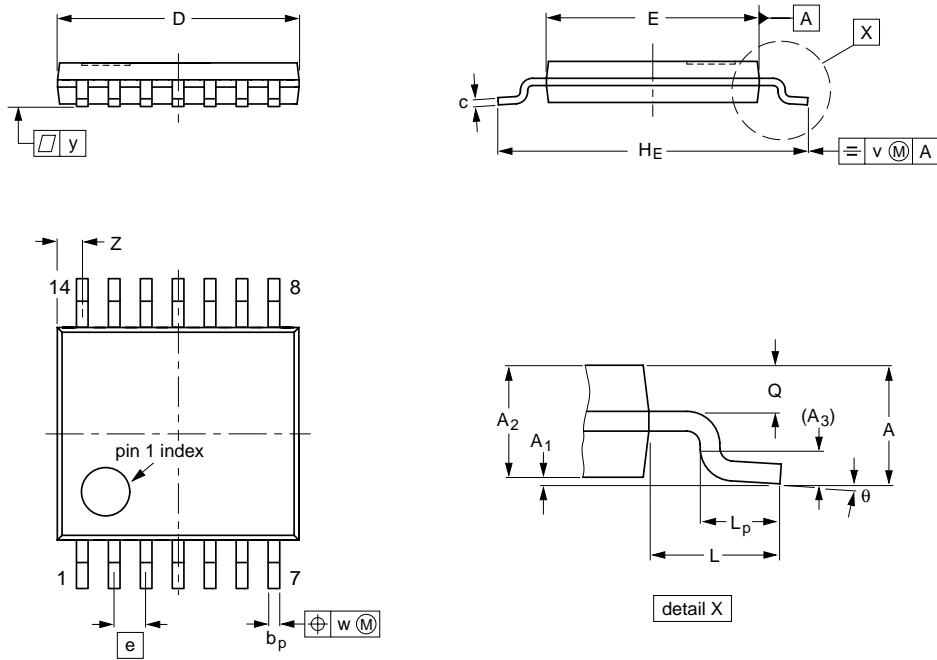
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT337-1		MO-150				99-12-27 03-02-19

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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

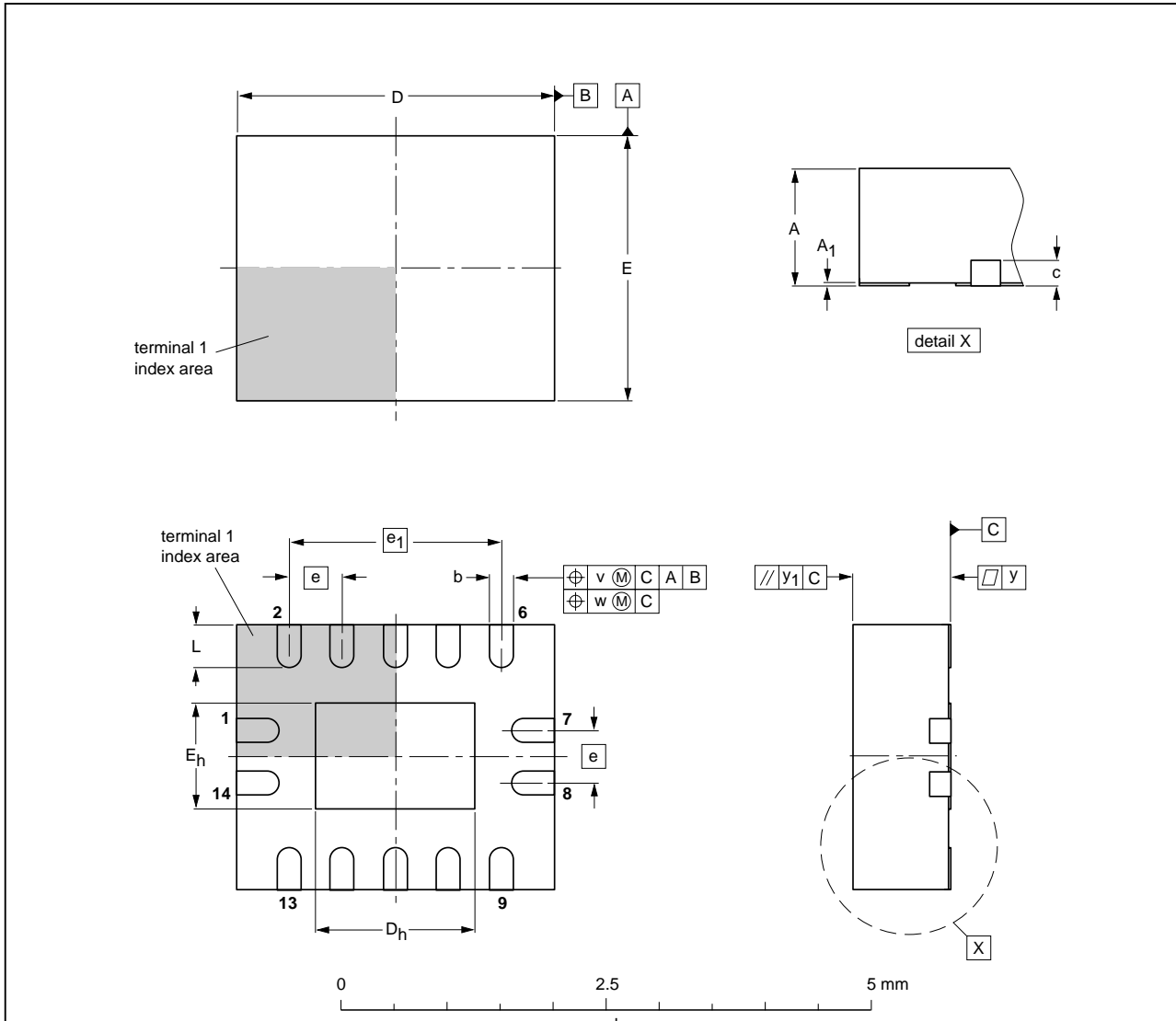
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	IEC	JEDEC	JEITA		
SOT402-1		MO-153			99-12-27 03-02-18

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DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1



DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	L	v	w	y	y ₁
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	1.65 1.35	2.6 2.4	1.15 0.85	0.5	2	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT762-1	---	MO-241	---		02-10-17 03-01-27

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